

DESCRIPTION

The MXD065N03 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

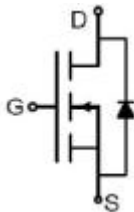
GENERAL FEATURES

- $V_{DS}=30V$, $I_D=50A$
 $R_{DS(ON)}(Typ.)=7.2m\Omega @ V_{GS}=10V$
 $R_{DS(ON)}(Typ.)=11m\Omega @ V_{GS}=4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

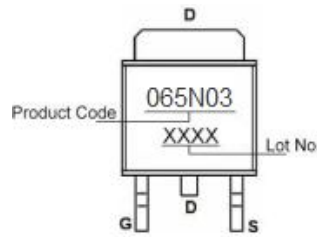
APPLICATION

- PWM applications
- Load switch
- Power management

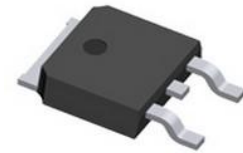
PINOUT



Schematic diagram



Marking and Pin Assignment



TO-252 top view

ORDERING INFORMATION

Device	Storage Temperature	Package	Devices Per Reel
MXD065N03	-55°C to 175°C	TO-252	2500

KEY PERFORMANCE PARAMETERS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	30	V
Gate-Source Voltage ($V_{DS}=0V$)	V_{GS}	± 20	V
Drain Current-Continuous ($T_C=25^\circ C$) ^(Note1)	I_D	50	A
Drain Current-Continuous ($T_C=100^\circ C$)	I_D	35	A
Drain Current-Continuous@Current-Pulsed ^(Note2)	$I_{DM(pluse)}$	200	A
Maximum Power Dissipation ($T_C=25^\circ C$)	P_D	50	W
Maximum Power Dissipation ($T_C=100^\circ C$)	P_D	25	W
Single Pulse Avalanche Energy ^(Note3)	E_{AS}	90	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$

THERMAL CHARACTERISTIC

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	3	$^\circ C/W$

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3. E_{AS} condition: $T_J=25^\circ C, V_{DD}=30V, V_G=10V, R_G=25\Omega$,



N-Channel Enhancement Mode Power MOSFET **MXD065N03**

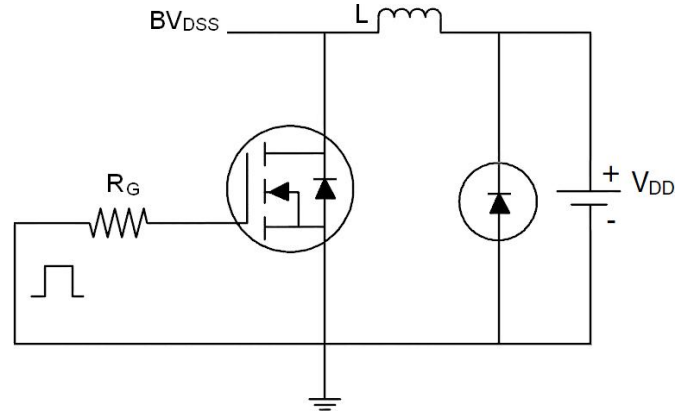
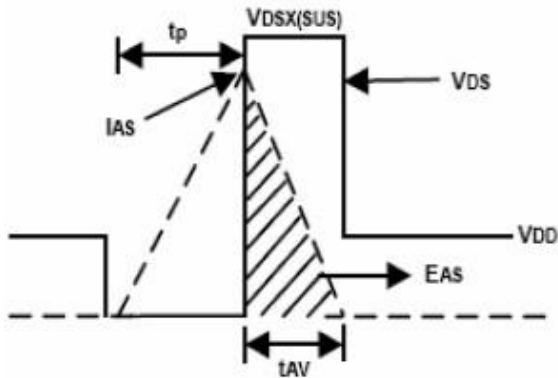


ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

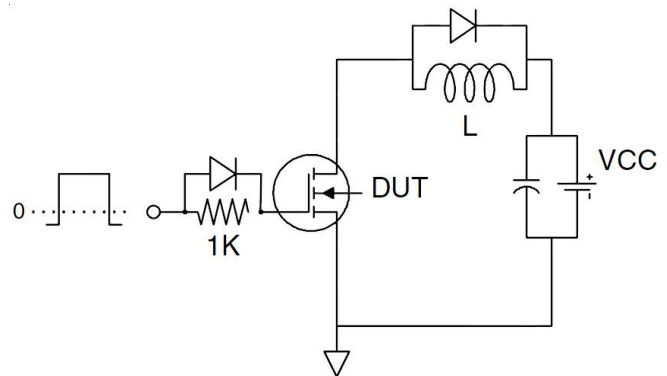
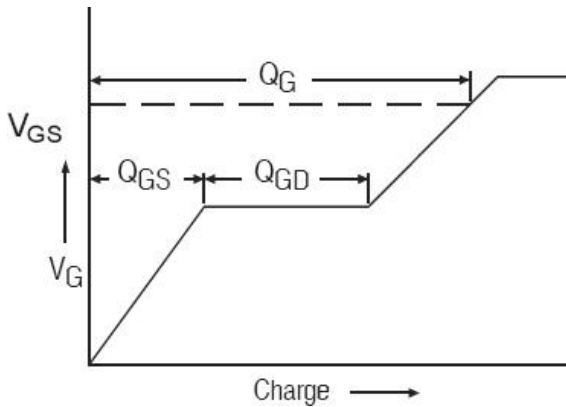
Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=30V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	7.2	9	m Ω
		$V_{GS}=4.5V, I_D=15A$	-	11	17	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=4.5V, I_D=15A$	10	20	-	S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS}=15V, V_{GS}=0V, F=1.0MHz$	-	1050	-	pF
Output Capacitance	C_{oss}		-	145	-	pF
Reverse Transfer Capacitance	C_{rss}		-	120	-	pF
Gate resistance	R_g	$V_{DS}=0V, V_{GS}=0V, F=1.0MHz$	-	2	-	Ω
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=12A, V_{GS}=25V$	-	22	-	nC
Gate-Source Charge	Q_{gs}		-	4	-	nC
Gate-Drain Charge	Q_{gd}		-	7	-	nC
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=15V, R_L=0.75\Omega, V_{GS}=10V, R_{GEN}=3\Omega$	-	7	-	nS
Turn-on Rise Time	t_r		-	22	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	t_f		-	5	-	nS
Source-Drain Diode Characteristics						
Source-Drain Current(Body Diode)	I_{SD}		-	-	50	A
Forward On Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=20A$	-	-	1.2	V

TEST CIRCUIT

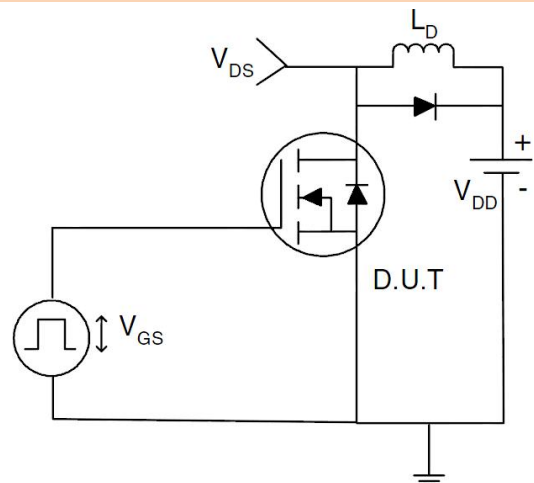
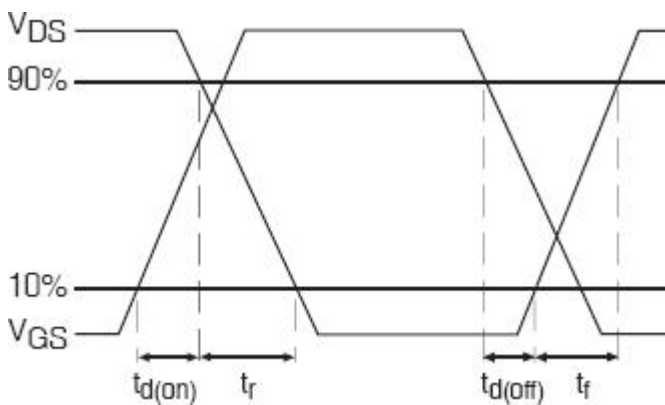
1) EAS Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



TYPICAL PERFORMANCE CHARACTERISTICS

Figure1. Output Characteristics

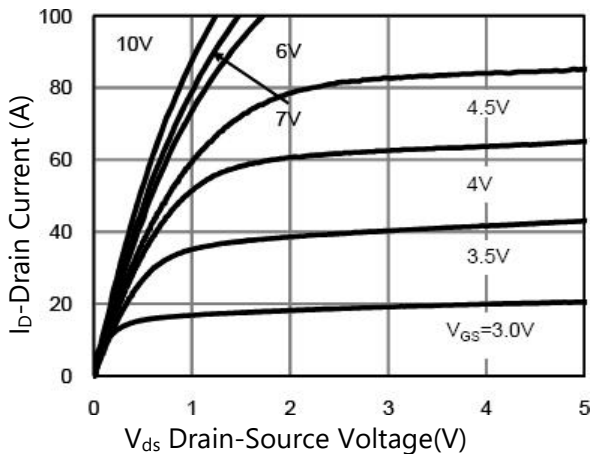


Figure2. Transfer Characteristics

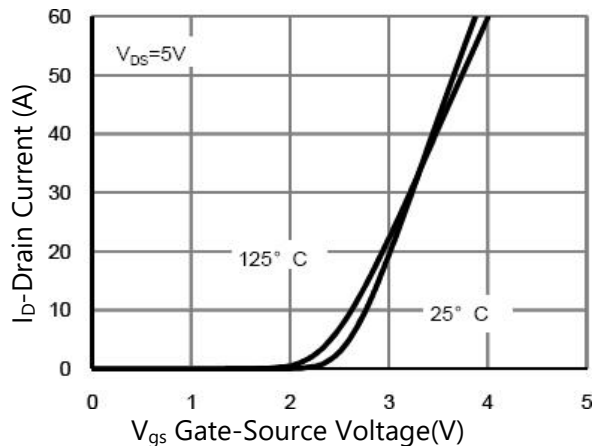


Figure3. BV_{DSS} vs Junction Temperature

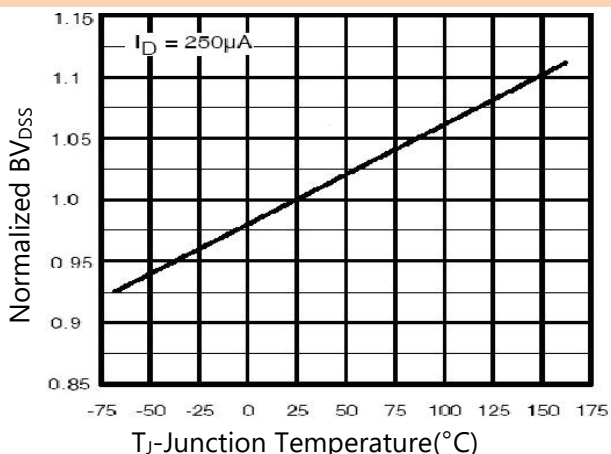


Figure4. Drain Current

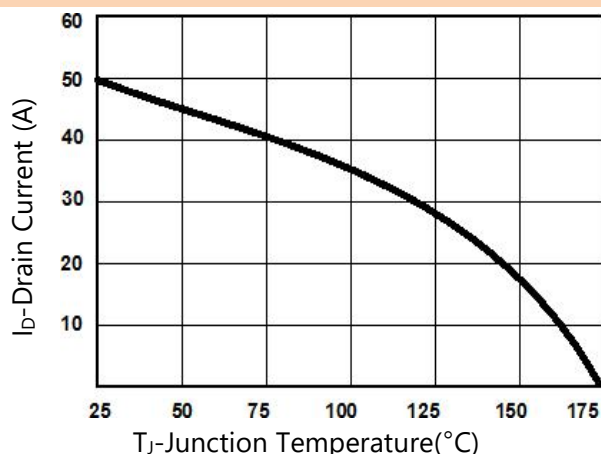


Figure5. $V_{GS(th)}$ vs Junction Temperature

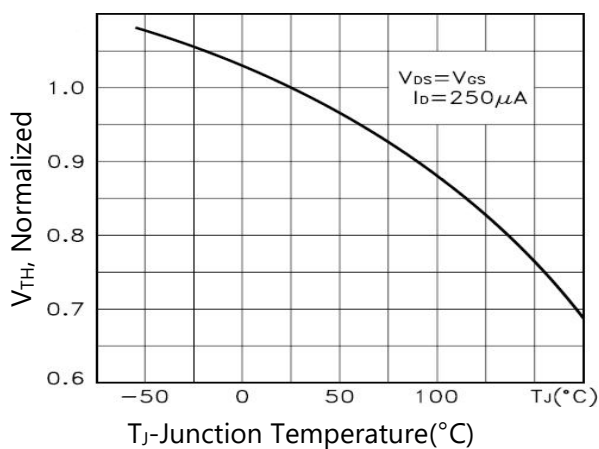
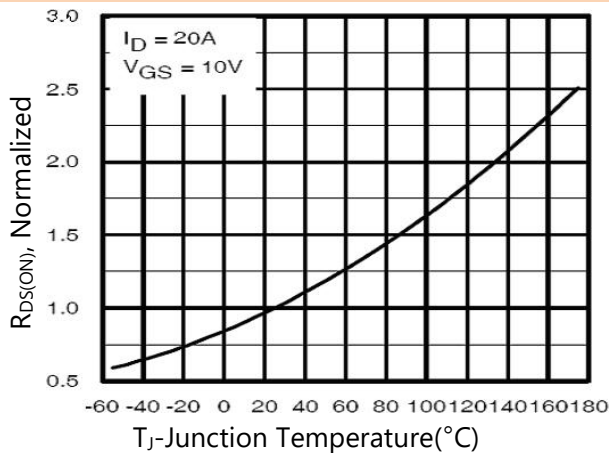


Figure6. $R_{DS(ON)}$ vs Junction Temperature



TYPICAL PERFORMANCE CHARACTERISTICS

Figure7. Gate Charge Waveforms

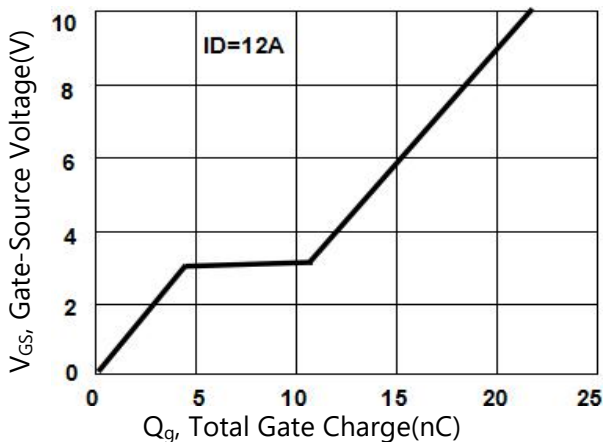


Figure8. Capacitance

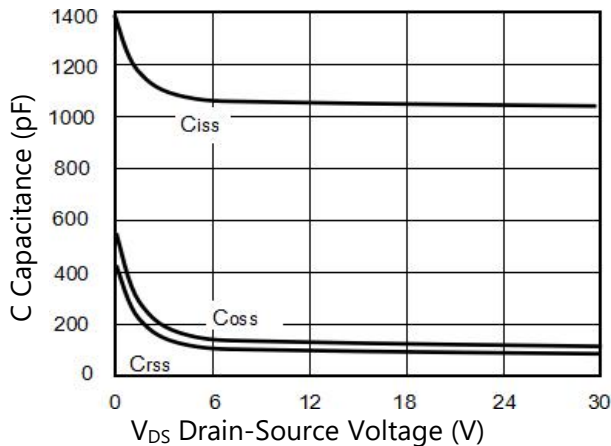


Figure9. Body Diode Forward

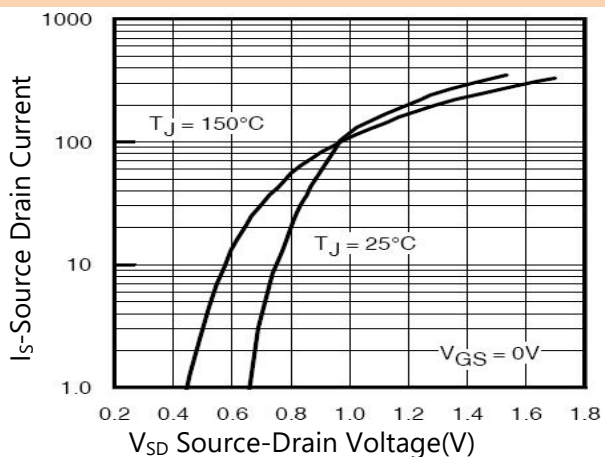


Figure10. Maximum Safe Operating Area

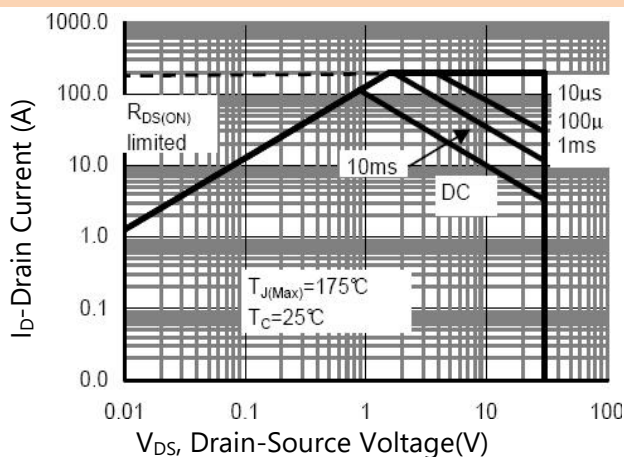
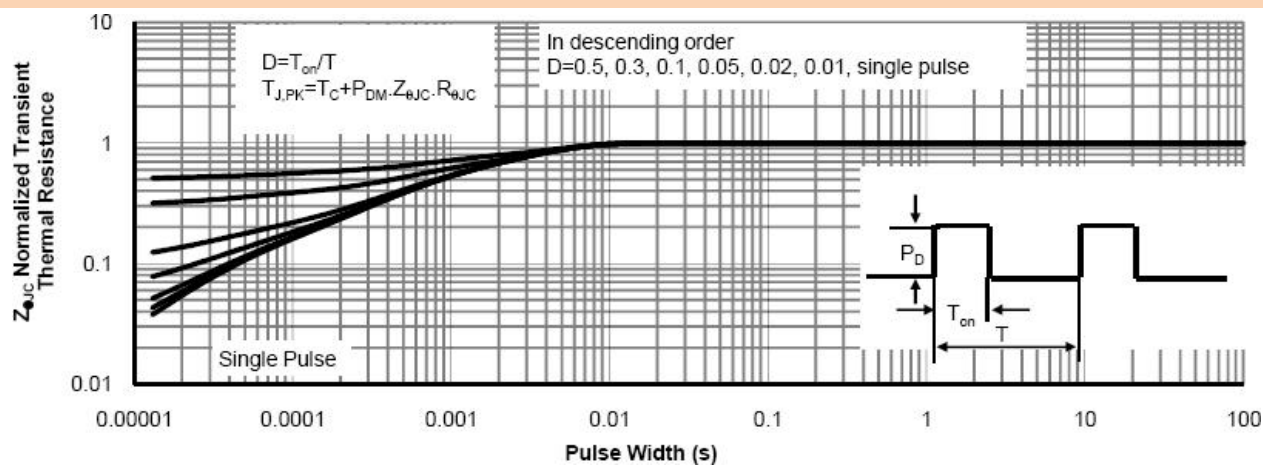
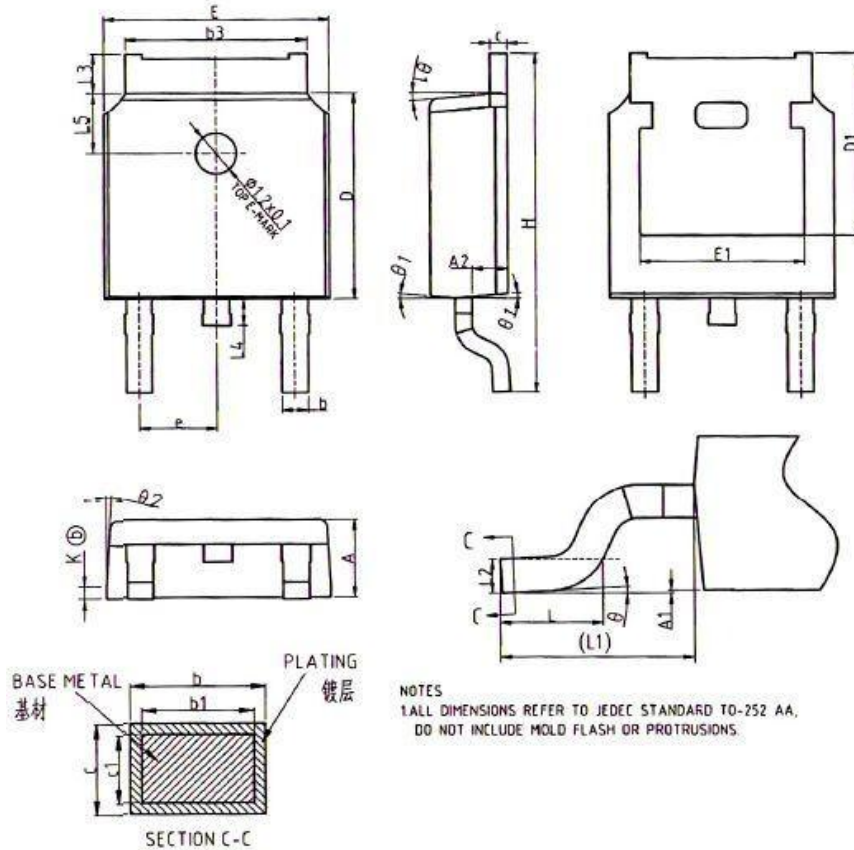


Figure11. Normalized Maximum Transient Thermal Impedance



PACKAGE INFORMATION

TO-252



SYMBOL	COMMON DIMENSIONS IN MILLIMETERS			SYMBOL	COMMON DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX		MIN	NOM	MAX
A	2.20	2.30	2.38	H	9.90	10.10	10.30
A1	0.00	-	0.10	L	1.40	1.50	1.70
A2	0.97	1.07	1.17	L1	2.90REF		
b	0.72	0.78	0.85	L2	0.51BSC		
b1	0.71	0.76	0.81	L3	0.90	-	1.25
b3	5.23	5.33	5.46	L4	0.60	0.80	1.00
c	0.47	0.53	0.58	L5	1.70	1.80	1.90
c1	0.46	0.51	0.56	θ	0°	-	8°
D	6.00	6.10	6.20	θ1	5°	7°	9°
D1	5.30REF			θ2	5°	7°	9°
E	6.50	6.60	6.70	K	0.40REF		
E1	4.70	4.83	4.92				
e	2.286BSC						